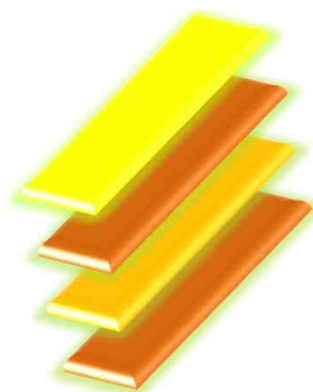


Technical Date Sheet

1. Product Name : PI Gold Conductive Film (New sputtering method)

2. Product No : EPFC-015NG

3. Structure



Au layer

Cu layer
Sputtered seed
(Ni/Cu alloy)

PI Film



Item	Reference
Au + Cu	2~2.5μm
PI FILM	12.5μm
Total Thickness	15μm

* Au 300A°

4. Characteristics

ITEM	STANDARD	REFERENCE
Material	Au + Cu + PI Film	
Thickness (μm)	15 ± 10%	
Width (mm)	250 ± 20	
Length (M/Roll)	50 - 100	
Color	Gold	
Surface resistivity (Ω/sq inch)	0.01-0.03	MIL-G-83528
Peel Strength (kg/cm)	Min 0.6	
RoHS	N.D.	

Storage

-Avoid direct sunlight &, store indoor under the required temperature and humidity constantly.
(Temperature : 22~28 °C , Humidity: 50±10 %RH)

Precautions

-Forbid handling with bare hands for protecting surface and recommend to use clear gloves.
-Be careful in handling it as excessive shock for prevent from surface damage.

Guaranty Period

-For 3 months from the date of delivery without opening paper box and for 1 month with opening paper box providing the condition of storage and precaution requested as above.